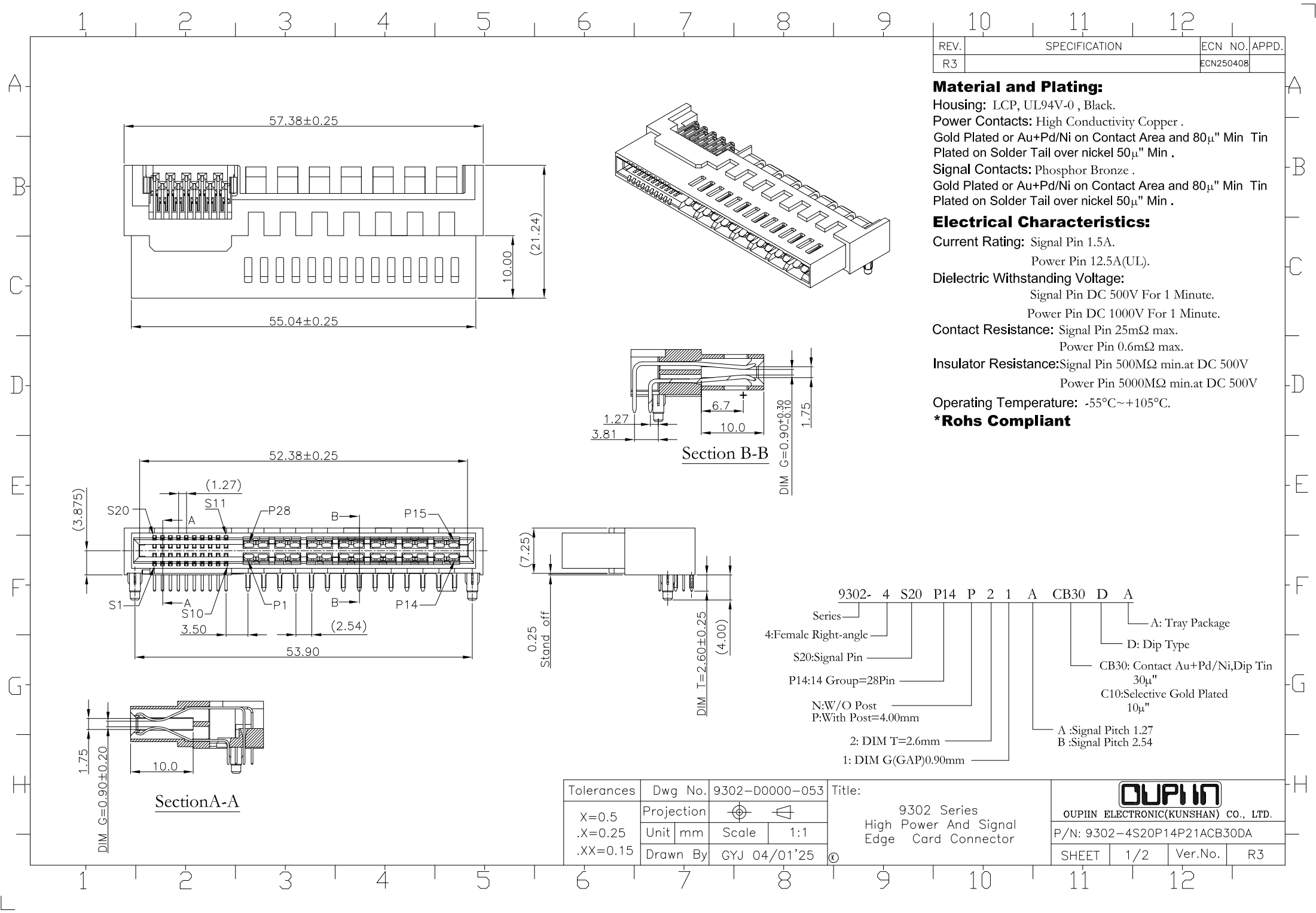




REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN250408	

Material and Plating:

Housing: LCP, UL94V-0 , Black.

Power Contacts: High Conductivity Copper .

Gold Plated or Au+Pd/Ni on Contact Area and 80μ" Min Tin Plated on Solder Tail over nickel 50μ" Min .

Signal Contacts: Phosphor Bronze .

Gold Plated or Au+Pd/Ni on Contact Area and 80μ" Min Tin Plated on Solder Tail over nickel 50μ" Min .

Electrical Characteristics:

Current Rating: Signal Pin 1.5A.

Power Pin 12.5A(UL).

Dielectric Withstanding Voltage:

Signal Pin DC 500V For 1 Minute.

Power Pin DC 1000V For 1 Minute.

Contact Resistance: Signal Pin 25mΩ max.

Power Pin 0.6mΩ max.

Insulator Resistance:Signal Pin 500MΩ min.at DC 500V

Power Pin 5000MΩ min.at DC 500V

Operating Temperature: -55°C~+105°C.

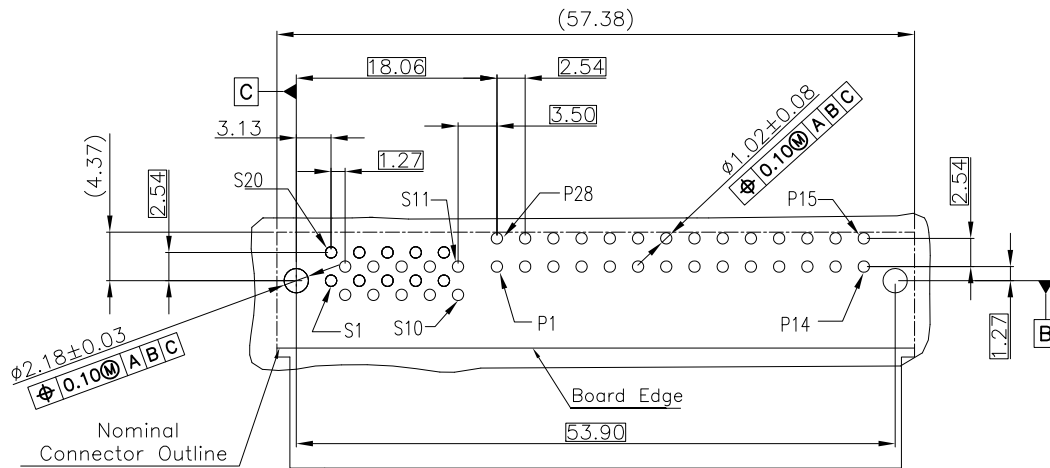
***Rohs Compliant**

Section B-B

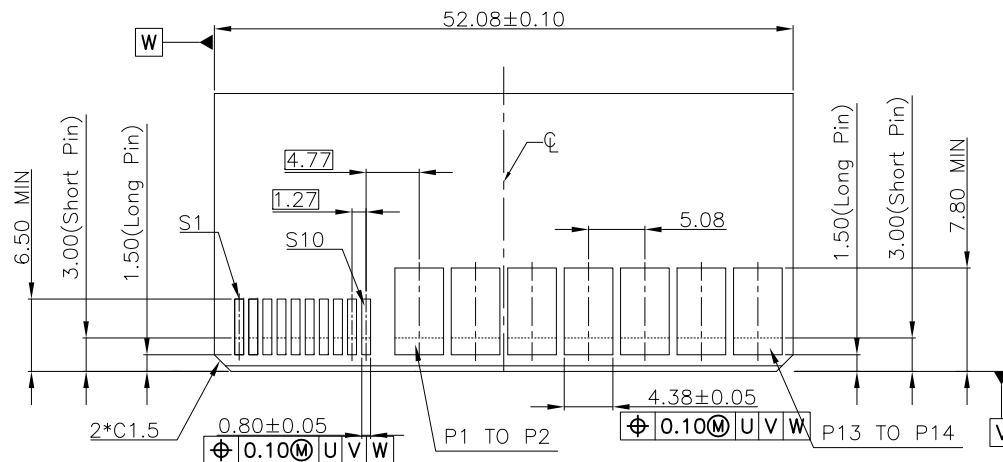
Section A-A

9302-	4	S20	P14	P	2	1	A	CB30	D	A
Series	4:Female Right-angle	S20:Signal Pin	P14:14 Group=28Pin	N:W/O Post P:With Post=4.00mm	2: DIM T=2.6mm	1: DIM G(GAP)0.90mm	A :Signal Pitch 1.27 B :Signal Pitch 2.54	CB30: Contact Au+Pd/Ni,Dip Tin 30μ"	D: Dip Type	A: Tray Package

Tolerances	Dwg No.	9302-D0000-053	Title:	9302 Series High Power And Signal Edge Card Connector	 OUPIN ELECTRONIC(KUNSHAN) CO., LTD. P/N: 9302-4S20P14P21ACB30DA SHEET 1/2 Ver.No. R3
X=0.5	Projection		Scale	1:1	
.X=0.25	Unit	mm	Scale	1:1	
.XX=0.15	Drawn By	GYJ 04/01'25	Scale	1:1	



P.C. Board Layout
(Tolerance:±0.05)



Recommended Mating Board Foot Print
(Tolerance:±0.05)

REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN250408	

Tolerances	Dwg No.	9302-D0000-053	Title:
X=0.5	Projection		9302 Series
.X=0.25	Unit mm	Scale 1:1	High Power And Signal
.XX=0.15	Drawn By	GYJ 04/01'25	Edge Card Connector

OUPIN ELECTRONIC(KUNSHAN) CO., LTD.			
P/N: 9302-4S20P14P21ACB30DA			
SHEET	2/2	Ver.No.	R3